

OPTICAL SUBASSEMBLY (OSA) FOR OPTOELECTRONIC MODULES, AND METHOD OF MAKING SAME

Abstract of the Disclosure

An optical subassembly for an optoelectronic module includes an adhesive interface
5 between a lens and an optoelectronic device, e.g., having a laser or a photoelectric receiver chip.
In addition to eliminating moisture condensation, the adhesive interface can eliminate damage to
a structural adhesive that may occur when air of a conventional interface expands as the
structural adhesive is cured. The adhesive interface has optical transmittance at the
optoelectronic device's operating wavelength, e.g., 850nm. The lens surface shape is selected
10 based on the adhesive interface's refractive index. An adhesive is applied both to the lens and to
the optoelectronic device, which are then joined and the adhesive cured to form the adhesive
interface. The adhesive is cured by exposure to UV radiation and/or heat, for example.